



#### 30V P-CHANNEL ENHANCEMENT MODE MOSFET

#### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C		
-30V	$6.8 \text{m}\Omega$ @ $V_{GS} = -10V$	-50A		
	$13m\Omega$ @ $V_{GS} = -4.5V$	-36A		

### **Description and Applications**

This MOSFET has been designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Backlighting
- Power Management Functions
- DC-DC Converters

### **Features and Benefits**

- Low R<sub>DS(ON)</sub> Ensures On State Losses are Minimized
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies Just 33% of the Board Area Occupied by SO-8 Enabling Smaller End Product
- 100% Unclamped Inductive Switching (Test in Production)
   Ensures More Reliability
- HBM ESD Protection Level of 8kV Typical
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

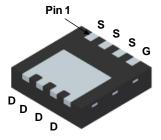
#### **Mechanical Data**

- Case: V-DFN3333-8 (Type B)
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Below Diagram Terminals: Finish –NiPdAu over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208
- Weight: 0.030 grams (Approximate)

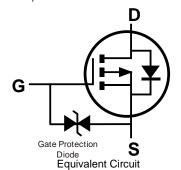




Top View



**Bottom View** 



#### Ordering Information (Note 5)

Part Number	Case	Packaging
DMP3007SCGQ-7	V-DFN3333-8 (Type B)	2,000/Tape & Reel
DMP3007SCGQ-13	V-DFN3333-8 (Type B)	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

### **Marking Information**



V07= Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 18 = 2018) WW = Week Code (01 to 53)



## **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	-30	V
Gate-Source Voltage			V <sub>GSS</sub>	±25	V
Continuous Drain Current (Note 8) V <sub>GS</sub> = -10V	Steady State	$T_C = +25$ °C $T_C = +70$ °C	I <sub>D</sub>	-50 -40	А
Maximum Continuous Body Diode Forward Current (Note 8)			Is	-40	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	-100	Α
Avalanche Current (Note 9) L = 1mH			I <sub>AS</sub>	-16	Α
Avalanche Energy (Note 9) L = 1mH			E <sub>AS</sub>	130	mJ

#### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	$P_D$	1.0	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	124	°C/W
Total Power Dissipation (Note 7)	T <sub>A</sub> = +25°C	P <sub>D</sub>	2.4	W
Thermal Resistance, Junction to Ambient (Note 7)  Steady State		R <sub>θJA</sub>	52	°C/W
Thermal Resistance, Junction to Case (Note 8)		R <sub>0</sub> JC	4.0	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

#### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 10)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-30	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-1	μΑ	$V_{DS} = -24V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 10)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-1.0		-3.0	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$	
Static Drain-Source On-Resistance	D	_	5.7	6.8	mΩ	$V_{GS} = -10V, I_D = -11.5A$	
Static Dialif-Source Off-Nesistance	R <sub>DS(ON)</sub>	_	8.0	13	mt2	$V_{GS} = -4.5V, I_D = -8.5A$	
Diode Forward Voltage	$V_{SD}$	_	-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 11)							
Input Capacitance	C <sub>iss</sub>	_	2,826	_	pF		
Output Capacitance	Coss	_	606	_	pF	$V_{DS} = -15V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	305	_	pF	1 = 1.0WH12	
Gate Resistance	$R_g$	_	23	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Qg	_	31.2	_	nC		
Total Gate Charge (V <sub>GS</sub> = -10V)	Qg	_	64.2	_	nC	V <sub>DS</sub> = -15V, I <sub>D</sub> = -11.5A	
Gate-Source Charge	$Q_{gs}$	_	10.6	_	nC	V <sub>DS</sub> = -15V, I <sub>D</sub> = -11.5A	
Gate-Drain Charge	$Q_{gd}$	_	11.6	_	nC		
Turn-On Delay Time	t <sub>D(ON)</sub>	_	4.8	_	ns	$V_{DD} = -15V$ , $V_{GS} = -10V$ , $R_g = 6\Omega$ , $I_D = -11.5A$	
Turn-On Rise Time	t <sub>R</sub>	_	4.3	_	ns		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	306	_	ns		
Turn-Off Fall Time	t <sub>F</sub>	_	125	_	ns		
Reverse Recovery Time	t <sub>RR</sub>	_	19	_	ns	1 44 54 41/44 4004/:	
Reverse Recovery Charge	Q <sub>RR</sub>	_	9.8		nC	I <sub>S</sub> = -11.5A, dI/dt = 100A/μs	

6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.7. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.8. Thermal resistance from junction to soldering point (on the exposed drain pad). Notes:

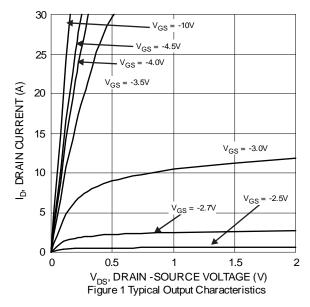
9.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J = +25$ °C.

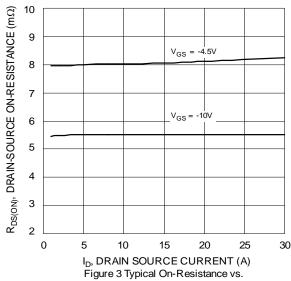
10. Short duration pulse test used to minimize self-heating effect.

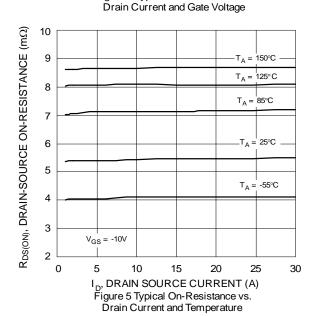
11. Guaranteed by design. Not subject to product testing.

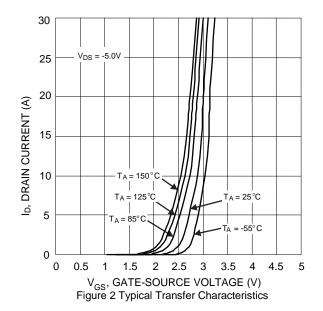
DMP3007SCGQ 2 of 7 Document number: DS41006 Rev. 2 - 2 Downloaded From Oneyac.com

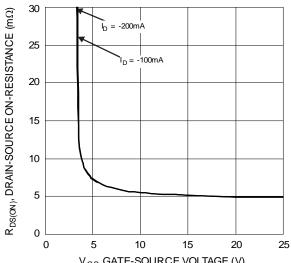




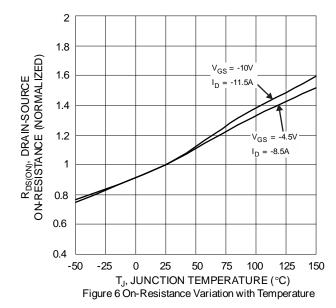






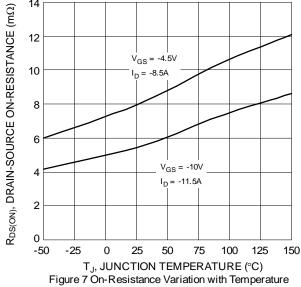


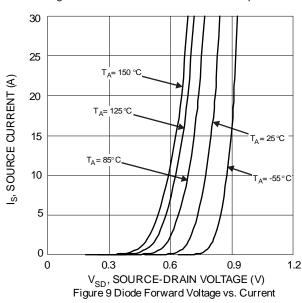
V<sub>GS</sub> GATE-SOURCE VOLTAGE (V) Figure 4 Typical Drain-Source On-Resistance vs. Gate-Source Voltage

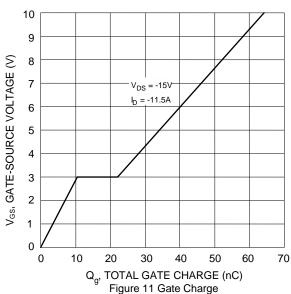


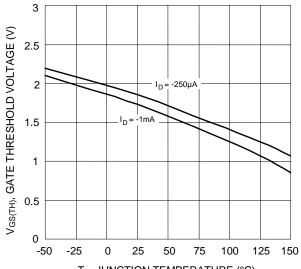
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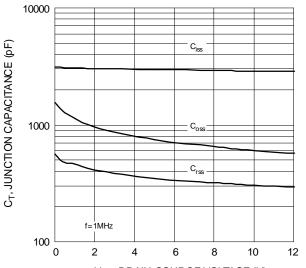




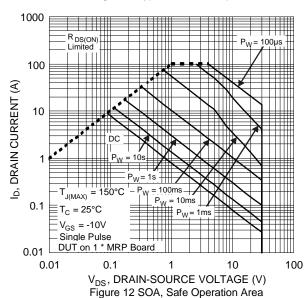




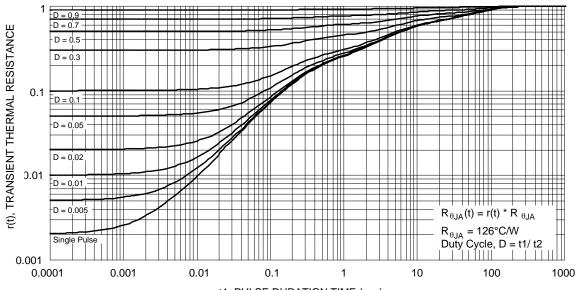
 $\label{eq:total_total} T_J, \, \text{JUNCTION TEMPERATURE (°C)}$  Figure 8 Gate Threshold Variation vs. Junction Temperature



V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V) Figure 10 Typical Junction Capacitance







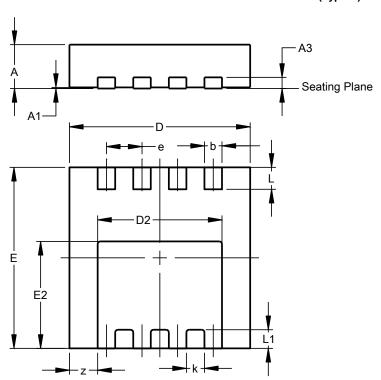
t1, PULSE DURATION TIME (sec) Figure 13 Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### V-DFN3333-8 (Type B)

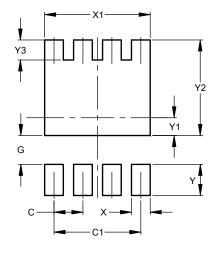


V-DFN3333-8					
(Type B)					
Dim	Min	Max	Тур		
Α	0.75	0.85	0.80		
A1	0.00	0.05	0.02		
A3			0.203		
b	0.27	0.37	0.32		
D	3.25	3.35	3.30		
D2	2.17	2.37	2.27		
Е	3.25	3.35	3.30		
E2	1.85	2.05	1.95		
е			0.65		
k	-		0.33		
L	0.35	0.45	0.40		
L1	-		0.34		
Z			0.515		
All Dimensions in mm					

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### V-DFN3333-8 (Type B)



Dimensions	Value (in mm)
С	0.650
C1	1.950
G	0.650
Х	0.420
X1	2.370
Υ	0.700
Y1	0.400
Y2	2.150
Y3	0.450



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July 2018

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